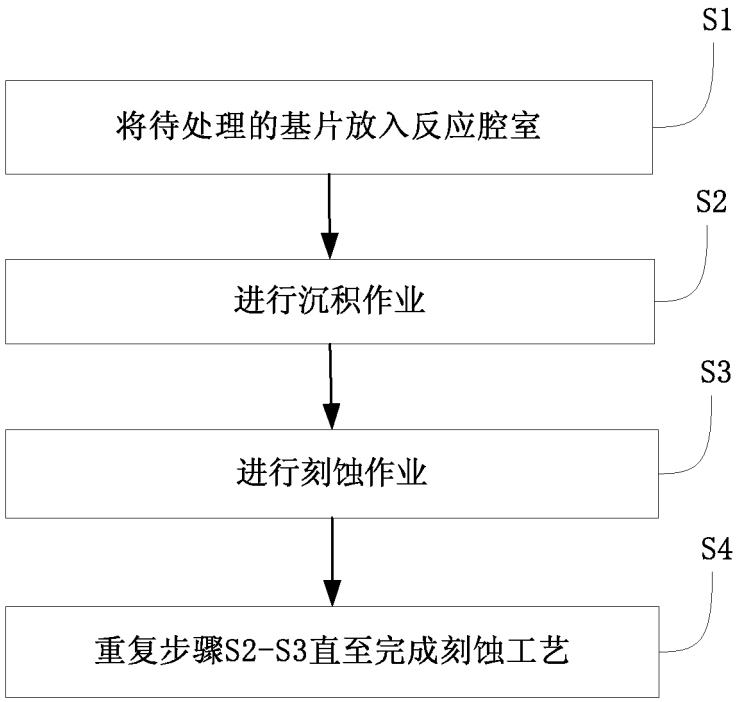

S1
将待处理的基片放入反应腔室
S2
进行沉积作业
S3
进行刻蚀作业
S4
重复步骤S2-S3直至完成刻蚀工艺

图 1

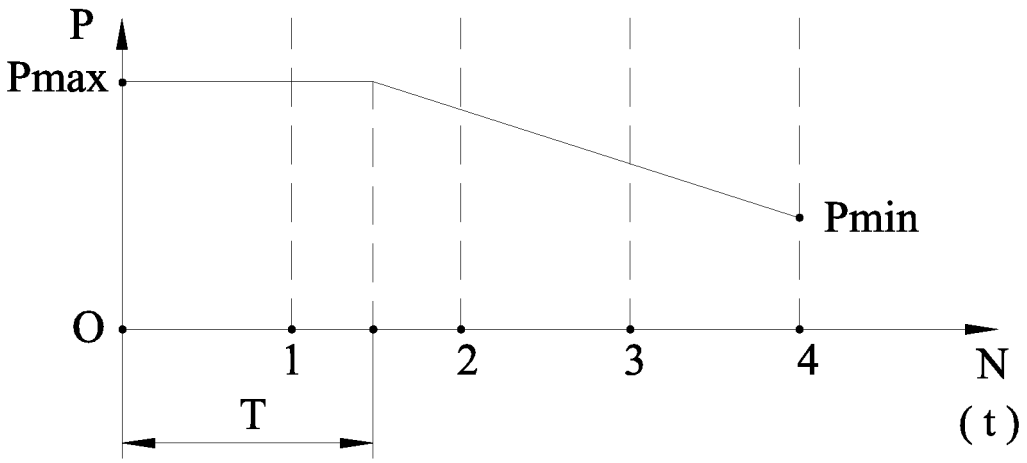

P
Pmax
Pmin
O
1
2
3
4
N
(t)
T

图 2a

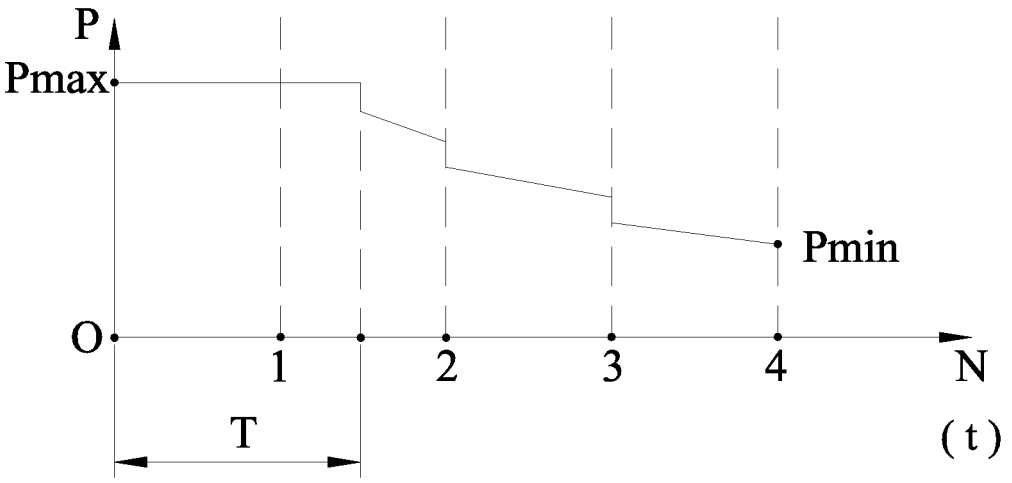

P
Pmax
Pmin
O
1
2
3
4
N
T
(t)

图 2b

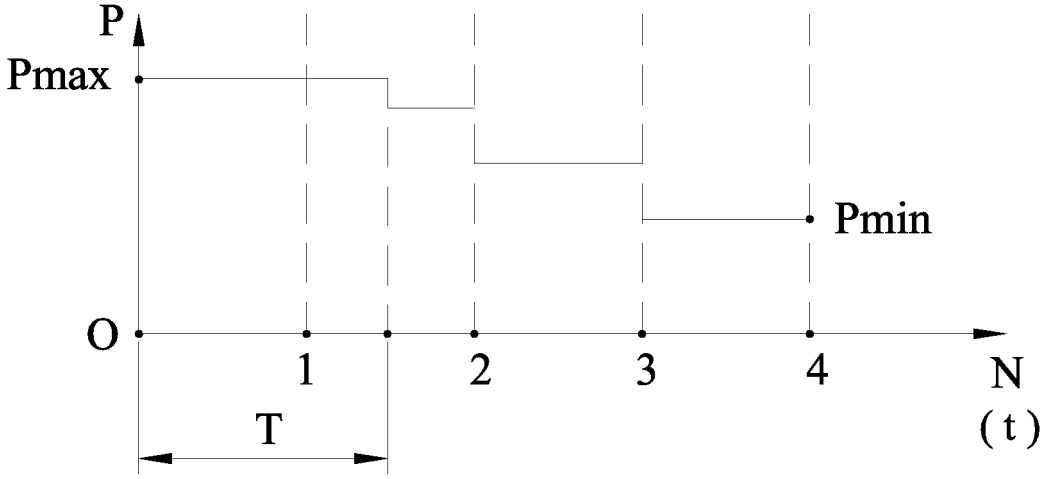

P
Pmax
Pmin
O
1
2
3
4
N
T
(t)

图 2c

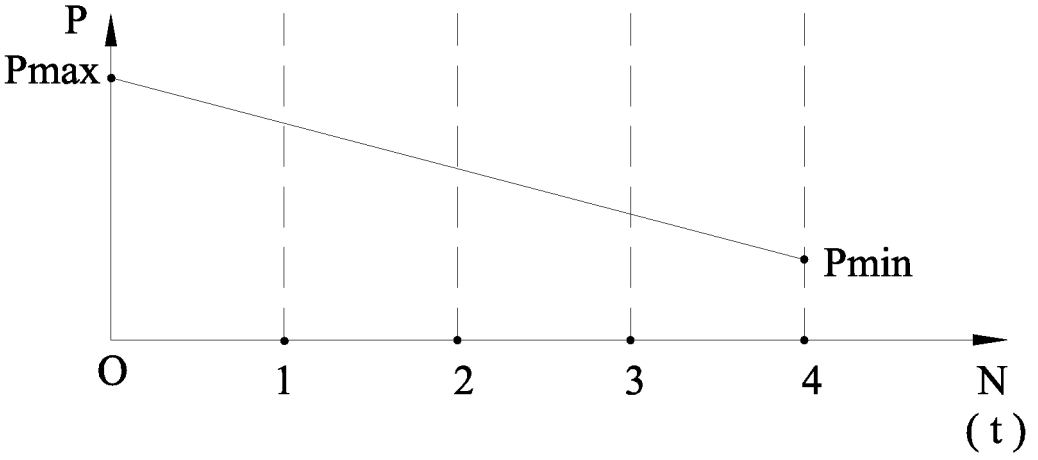

P
Pmax
Pmin
O
1
2
3
4
N
(t)

图 2d

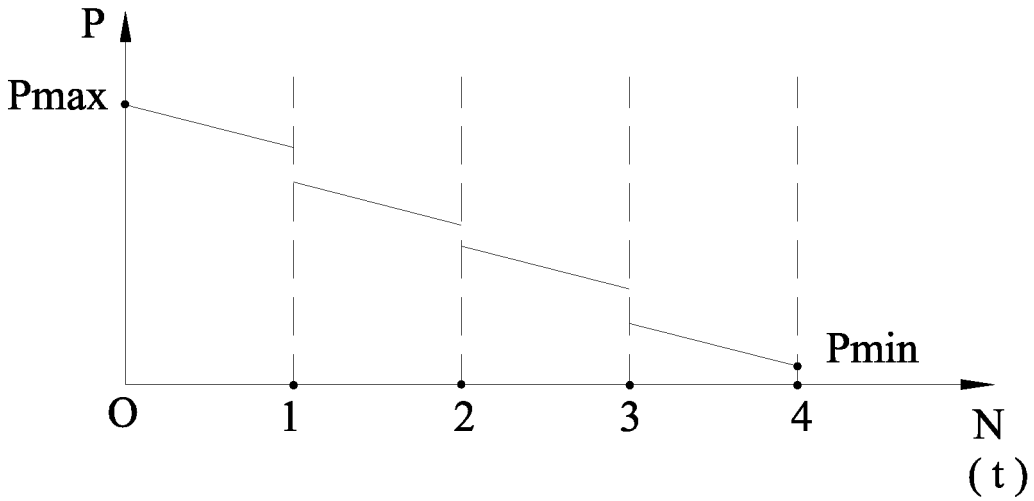


图 2e

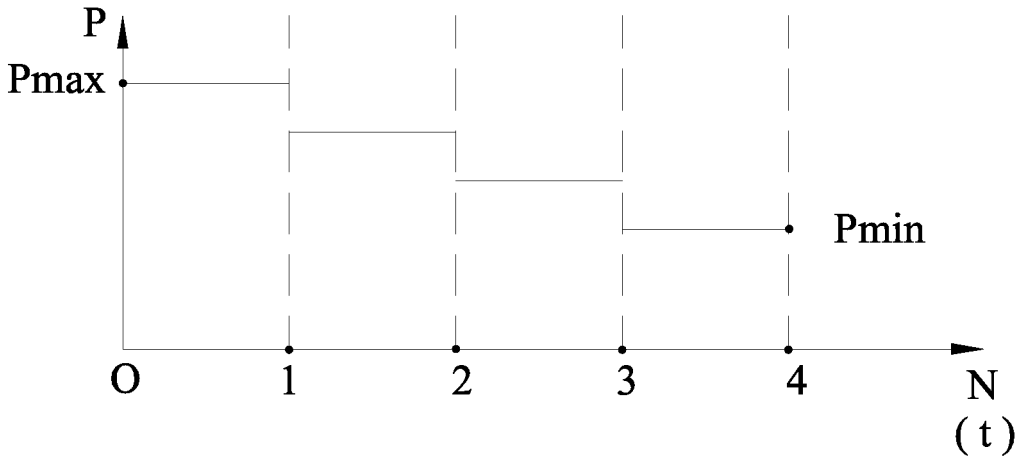


图 2f

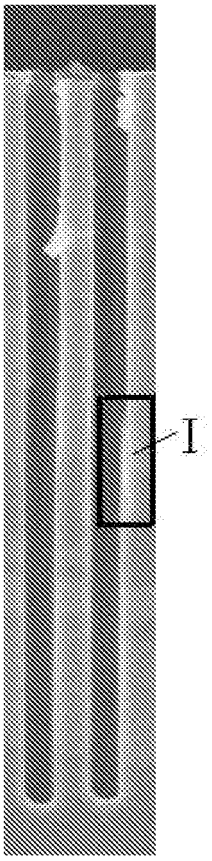


图 3a

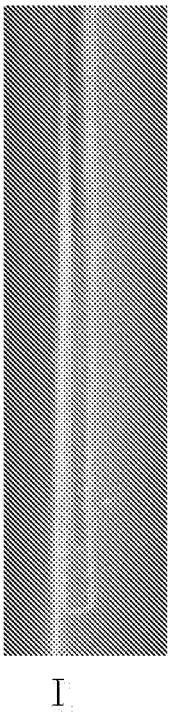


图 3b

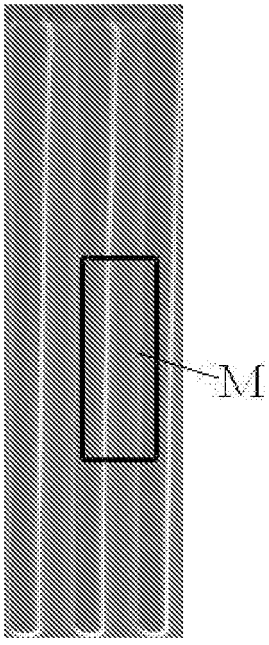


图 3c

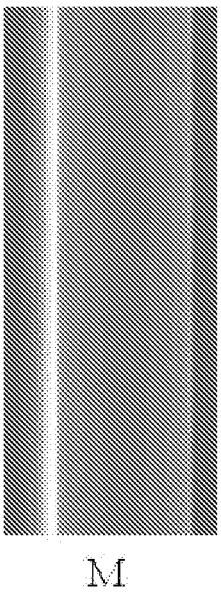


图 3d